

## **Product Change Notification / BLAS-18YLUC092**

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19-Apr-2023

# **Product Category:**

Memory

# **PCN Type:**

Manufacturing Change

# **Notification Subject:**

CCB 6206 and 2743.002 Final Notice: Qualification of MTAI as an additional assembly site and test location for selected AT25256Bxx, AT24C512xx, AT24CM01xx, and AT25M01xx device families available in 8L SOIJ (.208in) package.

## **Affected CPNs:**

BLAS-18YLUC092\_Affected\_CPN\_04192023.pdf BLAS-18YLUC092\_Affected\_CPN\_04192023.csv

## **Notification Text:**

**PCN Status:**Final Notification

PCN Type:Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of MTAI as an additional assembly site and test location for selected AT25256Bxx, AT24C512xx, AT24CM01xx, and AT25M01xx device families available in 8L SOIJ (.208in) package.

## **Pre and Post Change Summary:**

Note: Separate PCN was issued to qualify MTAI for CPNs AT24C512C-SHD-B,

AT24C512C-SHD-T, LIAL-27KKIA306	AT24C512C-	SHM-B, A	T24C512	C-SHM-T. R	efer to PCN #	
LIAL 27 MM/1300	Pre Ch	ange	Post Change			
Assembly Site	Philippine (P1/P2), Techn INC. Philip (P1/P2) (ANAP)		mkor nnology lippine P2), INC.	Microchip Technology Thailand (HQ) (MTAI)		
Wire material	Cu	PdCu	Cu	PdCu	Au	
Die attach material	8290		8290		8390A	
Molding compound material	G700A		G700A		G600V	
Lead frame material	CDA1	194	CDA194		CDA194	
DAP surface plating	PPF		PPF		Bare Cu	
Lead frame plating	NiPdAu		NiPdAu		Matte tin	
Lead frame	128 x 16		128 x 164 mils		140 x 160 mils	
paddle size	See	attached	pre and	post change	e comparison	

Note: This applies to all CPNs listed in the Affected CPN list.							
		Pre Change	Post	t Change			
Final Test Site		Amkor Technology Philippine (P1/P2), INC. (ANAP)  Amkor Technology Philippine (P1/P2), INC. (ANAP)		Microchip Technology Thailand (HQ) (MTAI)			
	BQM	2000	2000	2000			
	Pin 1 Orientation	Quadrant 1	Quadrant 1	Quadrant 1			
	Carrier Tape	Minor dimension change. See pre and post change for comparison.					
Tape and	Cover Tape	Minor dimension	Minor dimension change. See pre and post change for comparison.				
Reel	Diantia Dani	White	White	Dark Blue			
	Plastic Reel	Minor dimension change. See pre and post change for comparison.					
	Packing Static	Gray	Gray	Transparent			
	Sensitive Bag	With dimension	change. See pre and pos	t change for comparison.			
	Packing Method	See pre and post change for comparison.					
Tube	Pin 1 Orientation	See pre and post change for comparison.					

В	BQM	95	95	95		
С	Color	Green	Green	White		
T	Tube	Minor dimension change. See pre and post change for comparison.				
Р	Packing Method	See pre and post change for comparison.				

#### Impacts to Data Sheet:None

## Change ImpactNone

**Reason for Change:**To improve manufacturability and on-time delivery performance by qualifying MTAI as an additional assembly site and additional test location.

## **Change Implementation Status:**In Progress

Estimated First Ship Date:June 1, 2023 (date code: 2322)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

# Time Table Summary:

	April 2023			^		Jur	ne 20	)23			
Workweek	1	1 4	1 5	1 6	1 7		2 2	2	2 4	2 5	2 6
Qual Report Availability				Χ							
Final PCN Issue Date				Χ							
Estimated Implementation Date							Х				

## Method to Identify Change:Traceability code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:** April 19, 2023: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

PCN\_BLAS-18YLUC092\_Pre and Post Change\_Summary.pdf PCN\_BLAS-18YLUC092\_Test\_Qual\_Report\_Summary.pdf PCN\_BLAS-18YLUC092\_Assembly\_Qual\_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile, including opt out,</u> please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.



# **QUALIFICATION REPORT SUMMARY**

PCN #: BLAS-18YLUC092

Date: April 11, 2023

Qualification of MTAI as an additional assembly site and test location for selected AT25256Bxx, AT24C512xx, AT24CM01xx, and AT25M01xx device families available in 8L SOIJ (.208in) package.

**Purpose:** Qualification of MTAI as an additional assembly site and test location for selected AT25256Bxx, AT24C512xx, AT24CM01xx, and AT25M01xx device families available in 8L SOIJ (.208in) package.

**CCB No.**: 6206 and 2743.002

Test	Assembly lot	Wafer lot	Step	Result
I2C	MTAI233302771.000	MCSO519071706.000	Final Test @25C	
Correlation			100% QC @25C	PASSED
	NATA 1222222772 000	MCCOF10349710 000	Final Test @25C	
	MTAI233302772.000	MCSO519248719.000	100% QC @25C	

Test	Assembly lot	Wafer lot	Step	Result
	MTAI233202421.000	MCSO519050724.000	Final test @25C	
			100% QC @25C	
SPI Correlation	MTAI233202422.000	MCSO519050814.000	Final test @25C	Passed
			100% QC @25C	
	MTAI233102668.000	MCSO522507941.200	Final test @25C	
	WITAI2331U2008.UUU	IVIC3U3ZZ3U7941.ZUU	100% QC @25C	

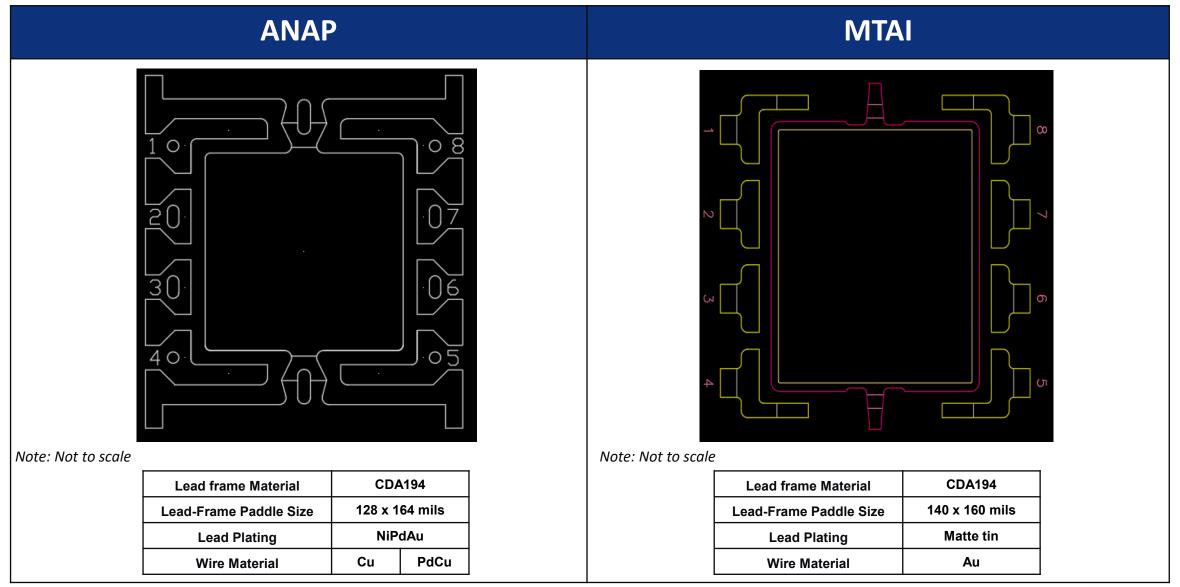
# CCB 6406 and 2743.002 Pre and Post Change Summary PCN# BLAS-18YLUC092



A Leading Provider of Smart, Connected and Secure Embedded Control Solutions

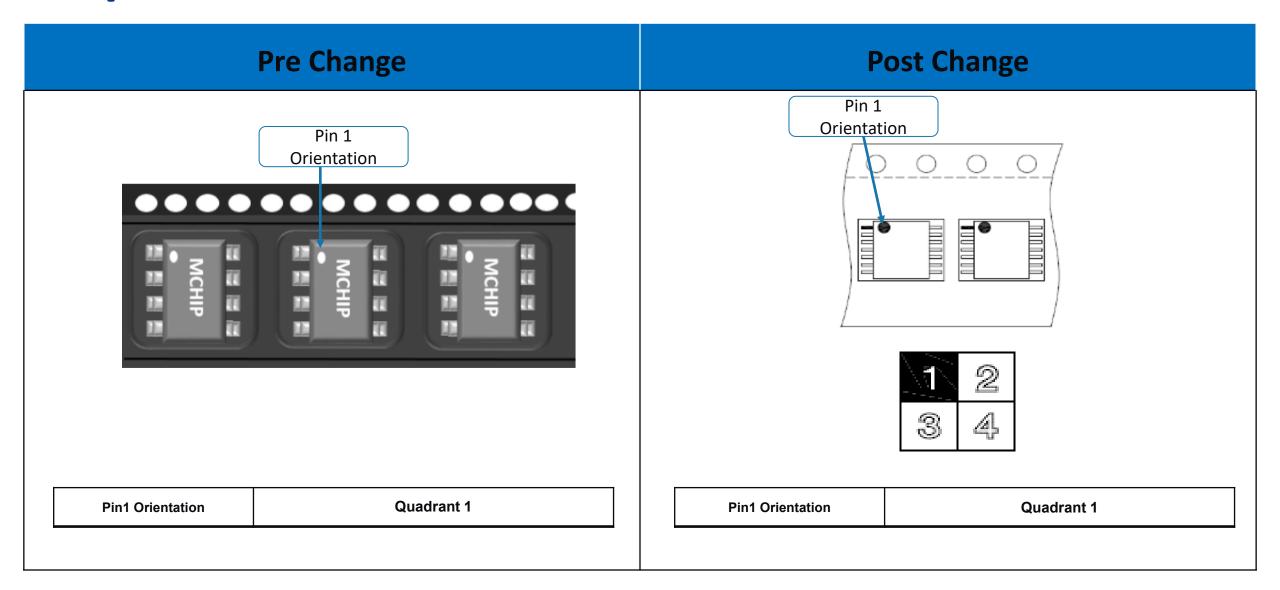


# **LEAD FRAME COMPARISON**



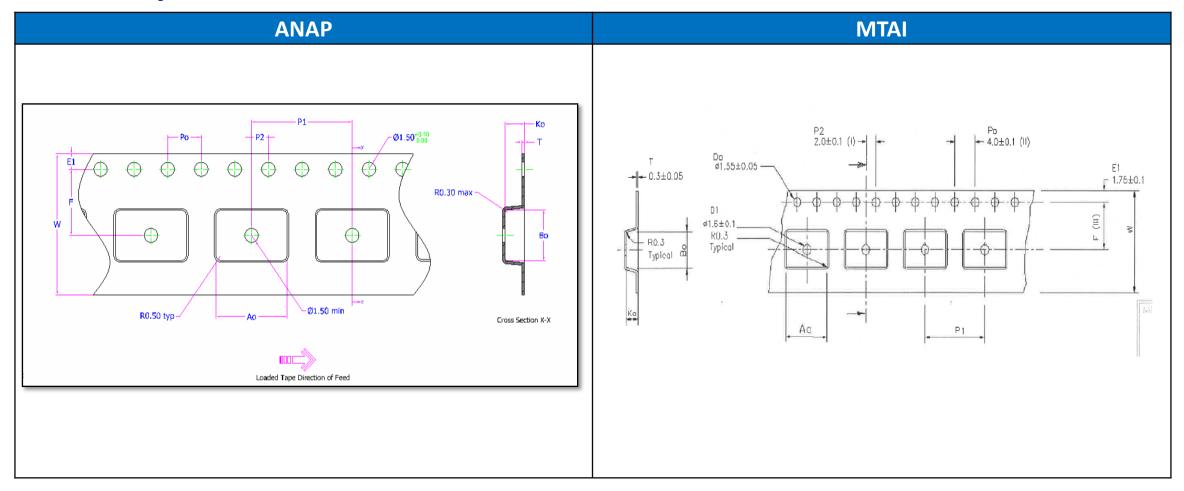


# **Tape and Reel Pin1 Orientation**





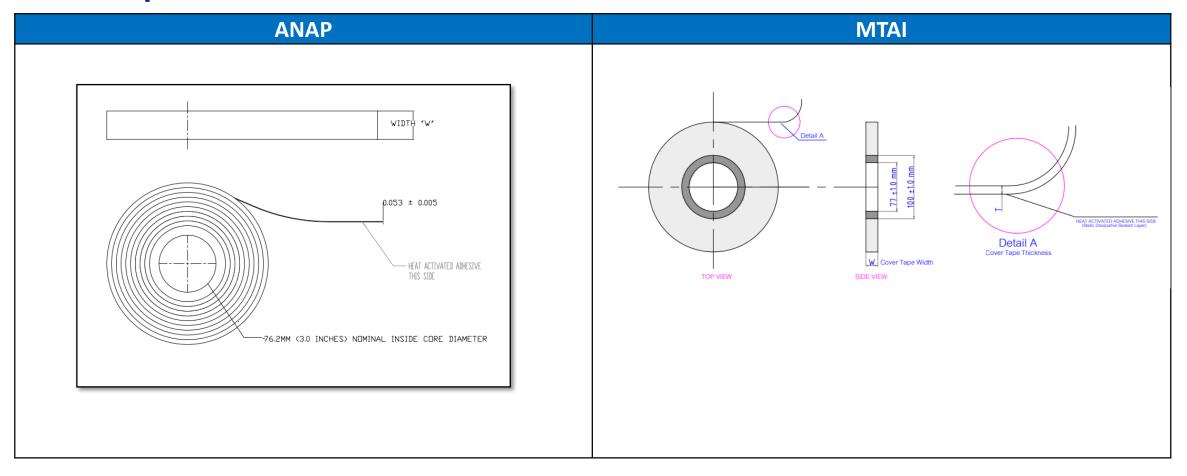
# **Carrier Tape**



Plant	W (mm.)	P (mm.)	A0 (mm.)	B0 (mm.)	K0 (mm.)	Thickness	BQM
ANAP	16.0 (+0.30, -0.10)	12.00 ( <u>+</u> 0.10)	8.45 <u>+</u> 0.10	5.70 ( <u>+</u> 0.10)	2.35 <u>+</u> 0.10	0.30 <u>+</u> 0.05	2000
MTAI	16 ±0.3	12 ±0.1	8.30 ±0.1	5.70 ±0.1	2.30 ±0.1	0.3 ±0.05	2000



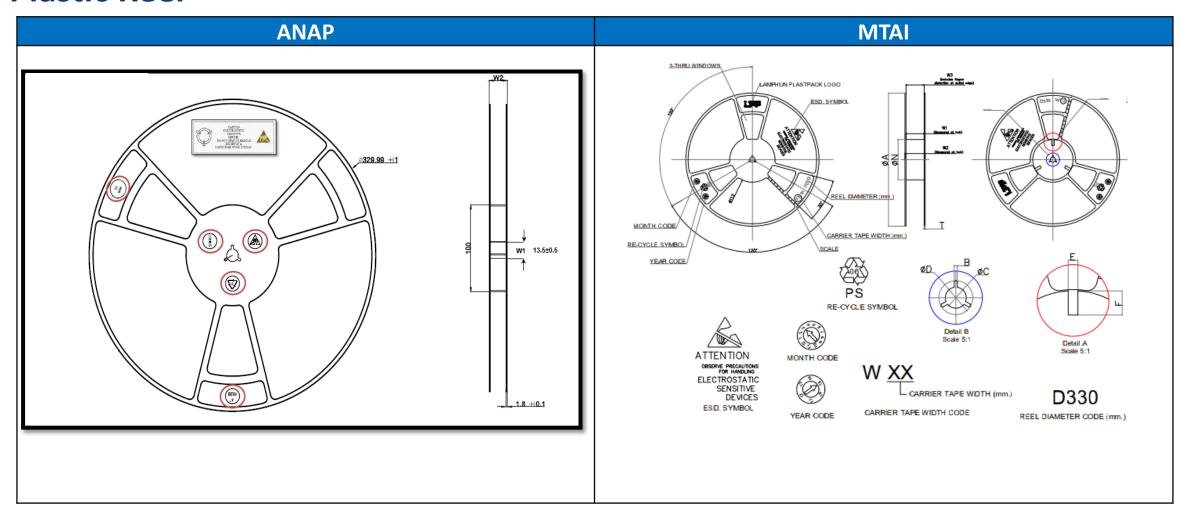
# **Cover Tape**



Plant	Width W (mm.)	Thickness T (mm.)	Colour	Sealing Methodology
ANAP	13.3 <u>+</u> 0.10	0.053 <u>+</u> 0.005	Gray	Heat Seal/ Heat Activated
MTAI	13.3 ±0.1	0.050 ±0.010	Clear	Heat Seal



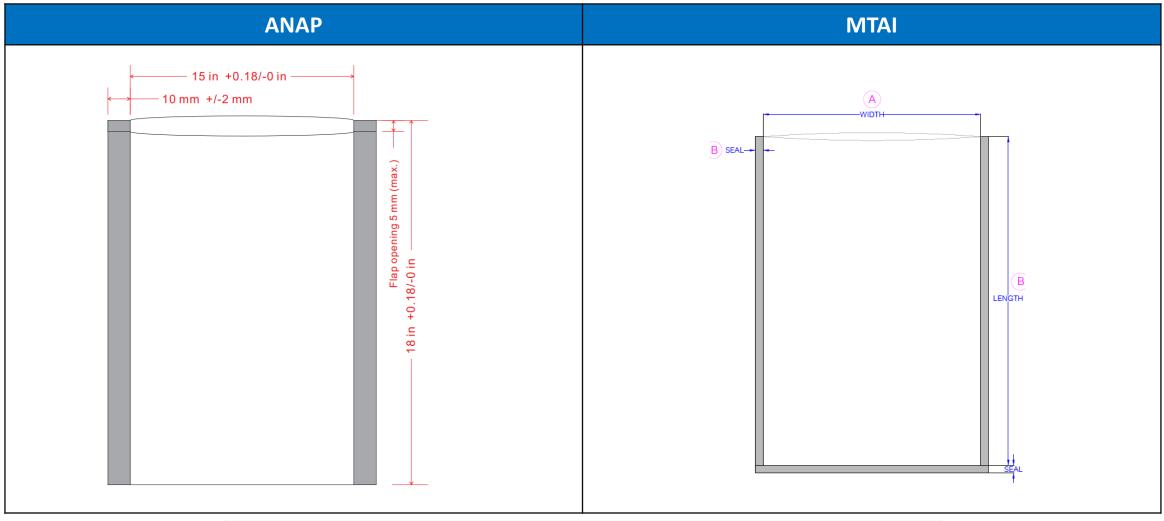
# **Plastic Reel**



Plant	Reel Diameter (mm.)	Reel Hub Size (mm)	Reel Width Max (mm.)	Colour
ANAP	329.99 <u>+</u> 1	100	19.4 <u>+</u> 0.8	White
MTAI	330 +/- 2.0	100 +/- 2.0	22.40 Max	Dark Blue



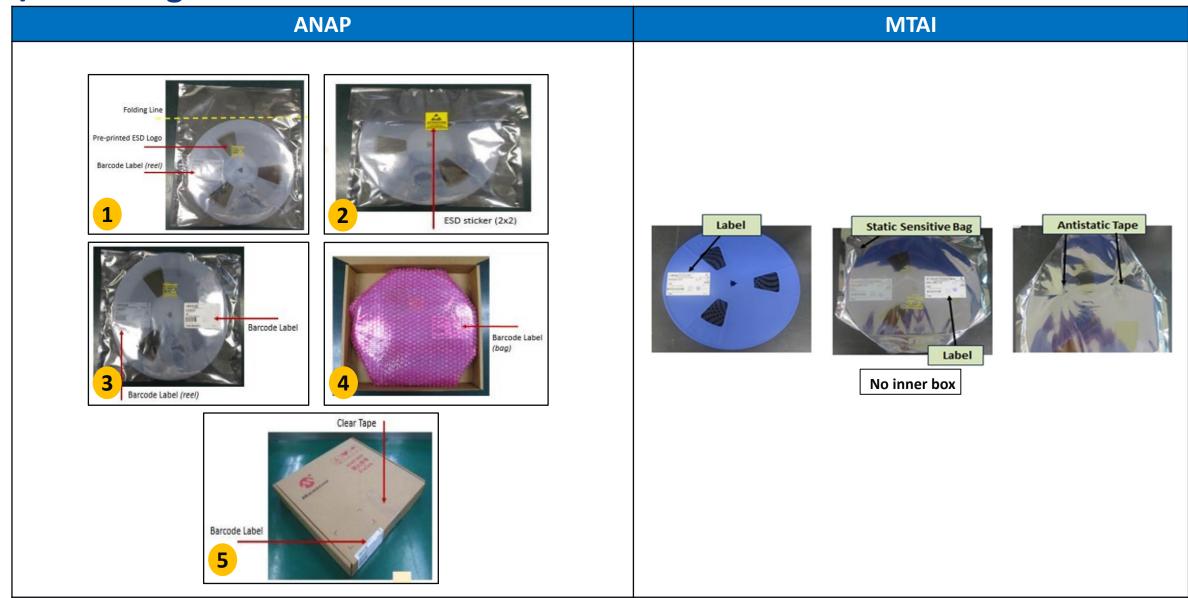
# **TAPE & REEL Packing Static Sensitive Bag**



Plant	Length (mm)	Width (mm)	Thickness (mils)	Colour
ANAP	457.2 +4.57/-0.00	381.0 +4.57/-0.00	3.0 ±0.3	Gray
MTAI	420 +5.0/-0.0	370 +5.0/-0.0	3.0 ±0.3	Transparent

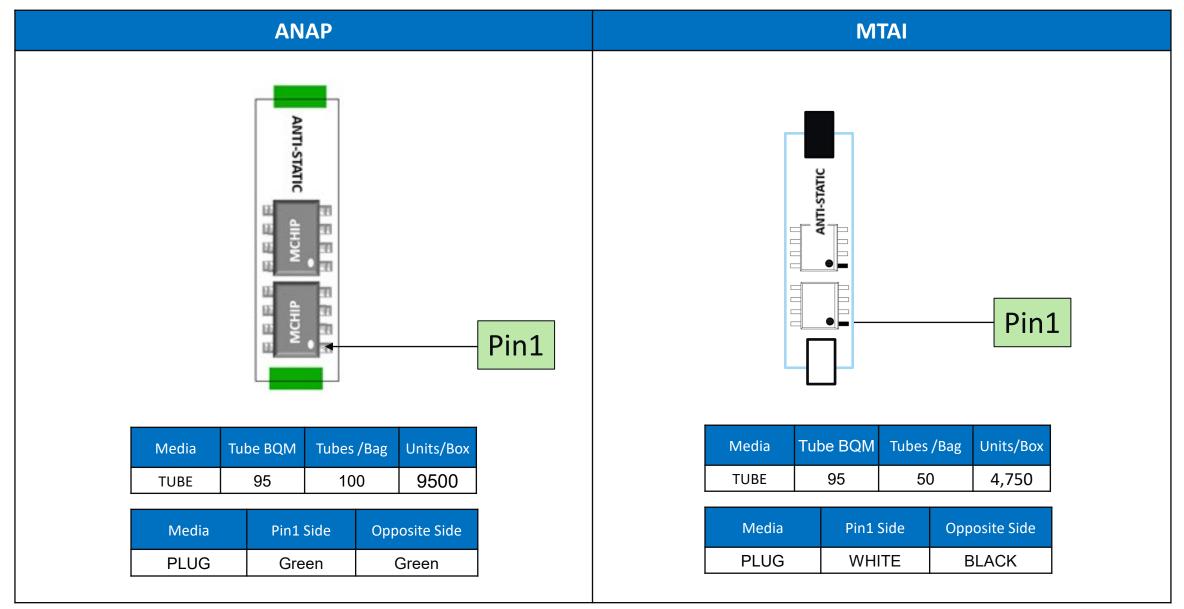


# T/R Packing Method



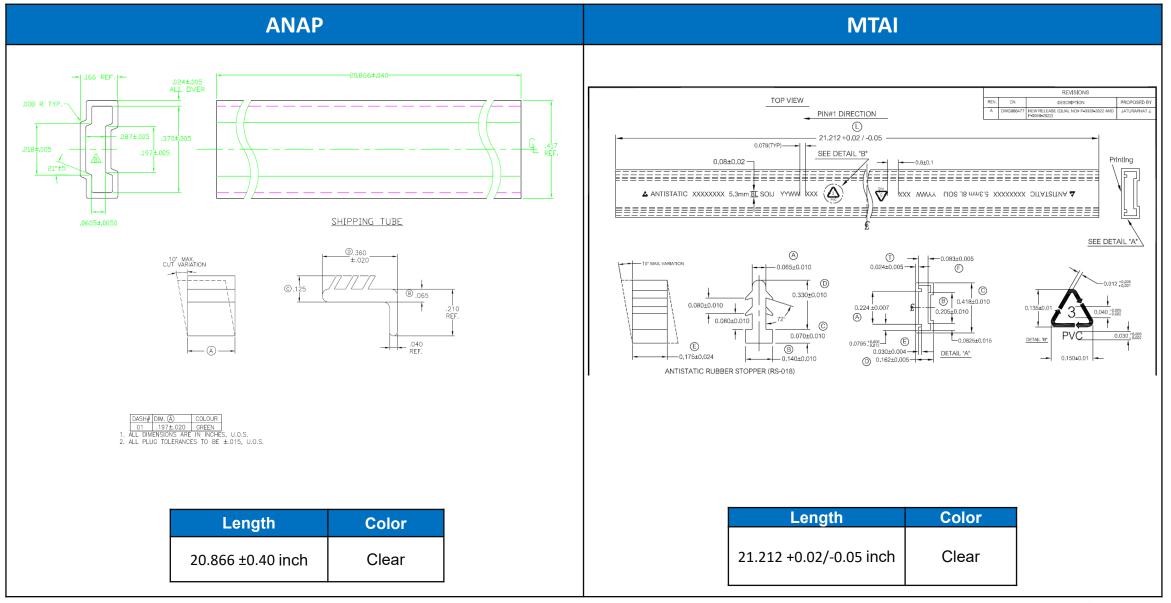


# **Tube Pin1 Orientation**



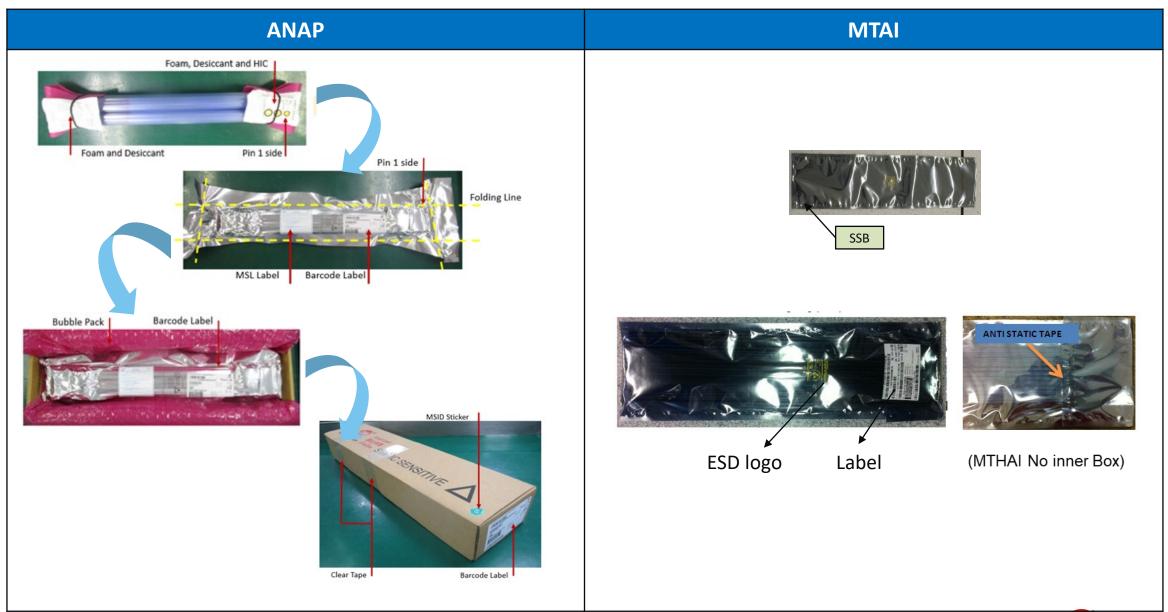


# **Tube**





# **TUBE Packing Method**



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## Affected Catalog Part Numbers (CPN)

AT25256B-SHL-B

AT25256B-SHL-T

AT24C512C-SHM-B

AT24C512C-SHD-B

AT24C512C-SHM-T

AT24C512C-SHD-T

AT24CM01-SHD-B

AT24CM01-SHM-B

AT24CM01-SHD-T

AT24CM01-SHM-T

AT25M01-SHM-B

AT25M01-SHM-T

Date: Tuesday, April 18, 2023